Materials Declaration

Package	LQFP
Body Size	10 X 10
LeadCount	64
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	9.31 E-03	32382
SiO2 Filler	86	1.00 E-01	348106
Phenol Resin	5	5.82 E-03	20239
Antimony_Sb2O3	0.4	4.66 E-04	1619
Brominated Resin	0.4	4.66 E-04	1619
Carbon Black	0.2	2.33 E-04	810

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	1.01 E-01	351829
Ni	3	3.16 E-03	10972
Si	0.65	6.84 E-04	2377
Mg	0.15	1.58 E-04	549

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	2.97 E-03	10331

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	4.90 E-03	17040

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.70 E-03	5900

Chip

	% of Chip	Weight (g)	PPM
Si	100	5.14 E-02	178844

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	1.30 E-03	4520
Ag Filler	74	3.70 E-03	12864

Package Totals

Weight (g)	PPM
2.88 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

STS-ST-C

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ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

Materials Declaration

Package	LQFP
Body Size	10 X 10
LeadCount	64
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	9.31 E-03	32382
SiO2 Filler	86	1.00 E-01	348106
Phenol Resin	5	5.82 E-03	20239
Antimony_Sb2O3	0.4	4.66 E-04	1619
Brominated Resin	0.4	4.66 E-04	1619
Carbon Black	0.2	2.33 E-04	810

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	1.01 E-01	351829
Ni	3	3.16 E-03	10972
Si	0.65	6.84 E-04	2377
Mg	0.15	1.58 E-04	549

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	2.97 E-03	10331

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	4.17 E-03	14484
Pb	15	7.35 E-04	2556

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.70 E-03	5900

Chip

	% of Chip	Weight (g)	PPM
Si	100	5.14 E-02	178844

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	1.30 E-03	4520
Ag Filler	74	3.70 E-03	12864

Package Totals

Weight (g)	PPM
2.88 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

STS-ST-A

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